

(0.635 mm) .025"

QSS SERIES

HIGH-SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSS

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze

Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating: Contact: 1.8 A per pin (2 pins powered)
 Ground Plane: 23.1 A per ground plane (1 ground plane powered)

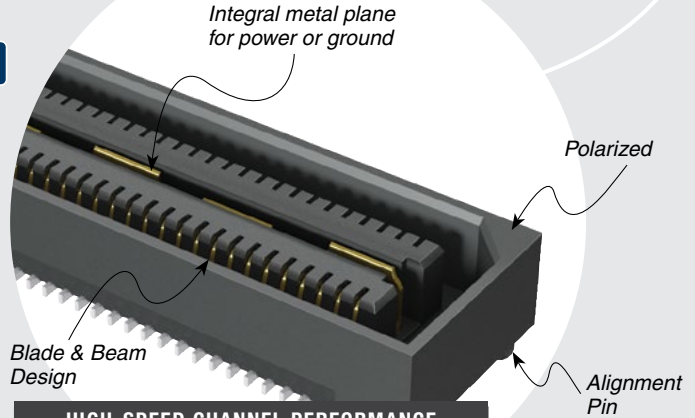
Operating Temp: -55 °C to +125 °C
Voltage Rating: 285 VAC
Max Cycles: 100

RoHS Compliant: Yes

Board Mates: QTS

Cable Mates: SQCD

Standoffs: SO



HIGH-SPEED CHANNEL PERFORMANCE

QSS/QTS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (025-050) (0.15 mm) .006" max (075)*
 *(.004" stencil solution may be available; contact IPG@samtec.com)
Board Stacking: For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

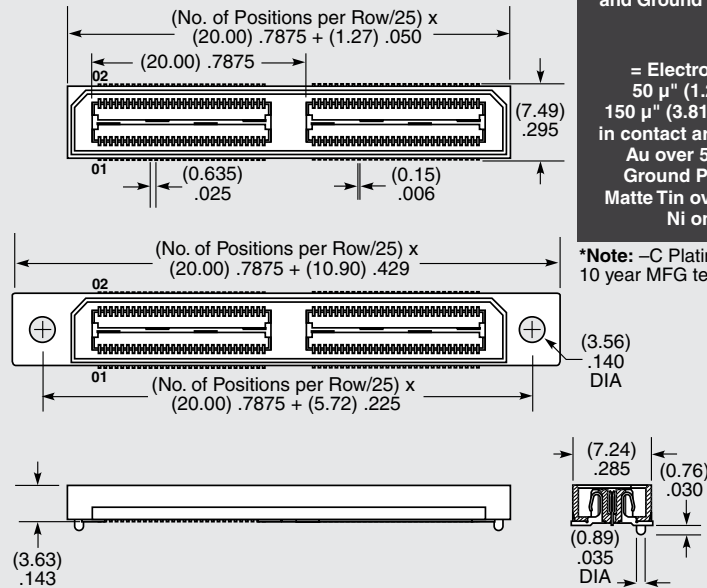


ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
 - 30 μ" (0.76 μm) Gold
 - Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
 - 100 & 125 positions per row
 - Edge Mount
 - -LS2 Locking screw hole for QTS-RA-LS2
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

QSS	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
	-025, -050, -075 (50 total positions per bank)		-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails			-GP = Guide Holes for mating with QTS-RA
			-L = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails			-K = (8.25 mm) .325" DIA Polyimide Film Pick & Place Pad
			-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails			-TR = Tape & Reel



*Note: -C Plating passes 10 year MFG testing

QTS LEAD STYLE	MATED HEIGHT WITH QSS
-01	(5.00) .197
-02	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.